## (12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

## (19) World Intellectual Property Organization International Bureau



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(43) International Publication Date 17 June 2004 (17.06.2004)

PCT

(10) International Publication Number WO 2004/051732 A1

(51) International Patent Classification7: 21/56, H05K 3/32, H01L 23/31

H01L 21/60,

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(21) International Application Number:

PCT/SG2002/000282

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(22) International Filing Date:

29 November 2002 (29.11.2002)

(81) Designated States (national): DE, US.

(25) Filing Language:

(26) Publication Language:

English

**English** 

**Declaration under Rule 4.17:** 

of inventorship (Rule 4.17(iv)) for US only

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**Published:** 

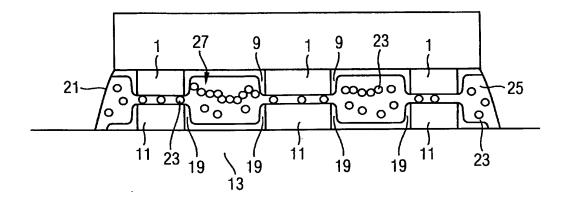
with international search report

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For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: ATTACHMENT OF FLIP-CHIPS TO SUBSTRATES



(57) Abstract: In a method of attaching a flip chip 3 to a substrate 13, insulating layers 9, 19 are formed on the lateral sides of the electrical contacts 1 of the flip chip 3 and the lateral sides of he electrical contacts 11 of the substrate 13. The flip-chip 3 is joined to the substrate 13 by a matrix 21 of insulating material 25 including electrically conductive particles 23. The insulating layers 9, 19 reduce the risk of the formation of horizontal conducting paths between the electrical contacts 1, 11.